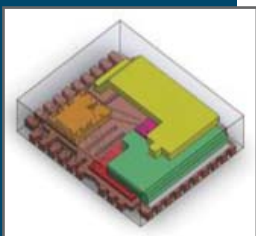
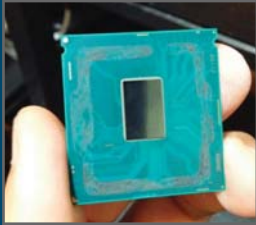


# Advanced Packaging Update: Market and Technology Trends

Vol. 1-0420



This issue of the Advanced Packaging Update features a detailed financial analysis of the assembly service providers and an outlook for the remainder of 2020. The impact of Covid-19 is analyzed and potential growth areas coming out of the pandemic are discussed. Sections on 5G infrastructure, Industrial IoT, and high-performance packaging trends are included. Forecast for units of BGAs and CSPs by package construction is provided. The CSP market is divided into laminate and leadframe (QFN) substrates. Unit growth projections for Cu clip, MIS, and package-on-package (PoP) are provided. Estimates of the market for each package type are based on input from captive as well as merchant assembly operations.

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